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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A method of producing a thin film circuit board used as a milli-wave or micro-wave module, the method comprising steps of:

- cleaning a substrate comprising dielectric ceramic, and having a thickness of 0.05 mm to 2 mm and a flexural strength of 500 kgf/cm² to 4000 kgf/cm²;
- forming a conductor film in a predetermined pattern on the substrate, said conductor film including at least one selected from Cu, Au, Ag, Al, Ni, Ti, Cr, Ni-Cr, Nb, and V;
- forming an insulating film on the substrate to cover the ~~entire~~ conductor film, said insulating film comprising at least one organic resin selected from polyimide, epoxy resins, benzocyclobutene resins, acrylic resins, and cyclic olefin resins, and having a ~~thickness of 20 μ m or greater, an area of 5 cm² or less per pattern, and a stress of 15 MPa to 60 MPa;~~
- curing and patterning the insulating film; and
- repeating the insulating film forming step and the insulating film curing and patterning step ~~more than at least once; wherein~~
- the insulating films have a total thickness of 20 μ m or greater.

Claim 2 (currently amended): A method of producing a thin film circuit board according to Claim 1, wherein the insulating film comprises a photosensitive organic film,

said insulating film forming step comprises a step of forming the photosensitive

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organic film on the substrate, and
said curing and patterning step comprises steps of
exposing and developing the photosensitive organic film by
photolithography, and
curing the photosensitive organic film.

Claim 3 (currently amended): A method of producing a thin film circuit board according to Claim 1, wherein the insulating film comprises a non-photosensitive organic film,

said insulating film forming step comprises a step of forming the non-photosensitive organic film on the substrate, and
said curing and patterning step comprises steps of
curing the non-photosensitive organic film,
forming an etching resist on the non-photosensitive organic film,
etching the non-photosensitive organic film by dry etching, and
removing the etching resist.